

# LNJ611W8WRU

## High Bright Surface Mounting Chip LED

3216 FD Type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter                     | Symbol    | Rating      | Unit             |
|-------------------------------|-----------|-------------|------------------|
| Power dissipation             | $P_D$     | 40          | mW               |
| Forward current               | $I_F$     | 10          | mA               |
| Pulse forward current *       | $I_{FP}$  | 40          | mA               |
| Reverse voltage               | $V_R$     | 5           | V                |
| Operating ambient temperature | $T_{opr}$ | -25 to +85  | $^\circ\text{C}$ |
| Storage temperature           | $T_{stg}$ | -30 to +100 | $^\circ\text{C}$ |

### ■ Lighting Color

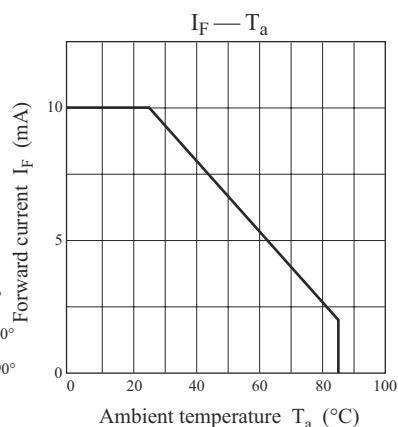
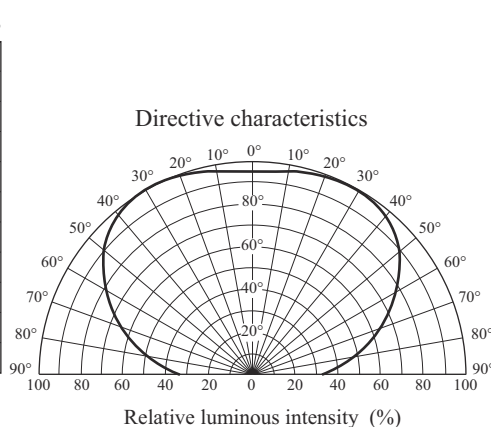
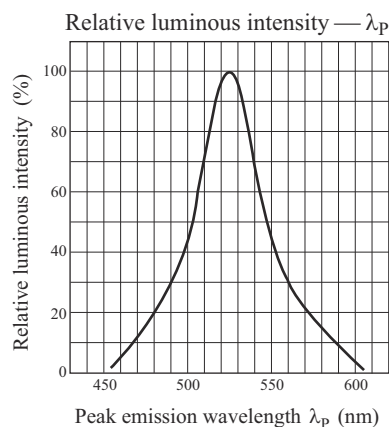
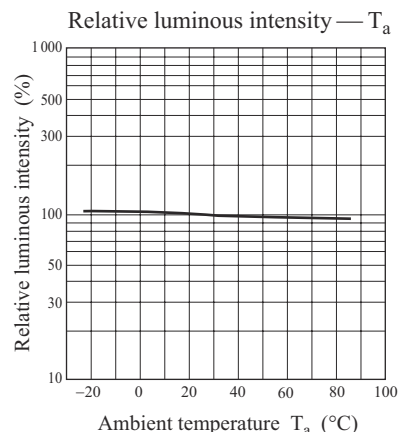
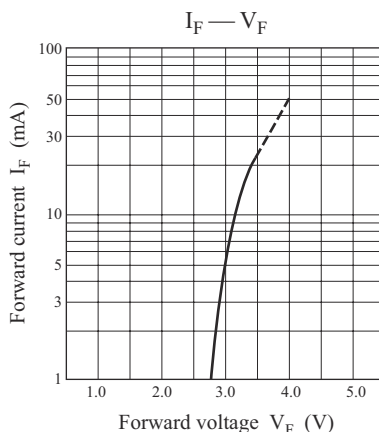
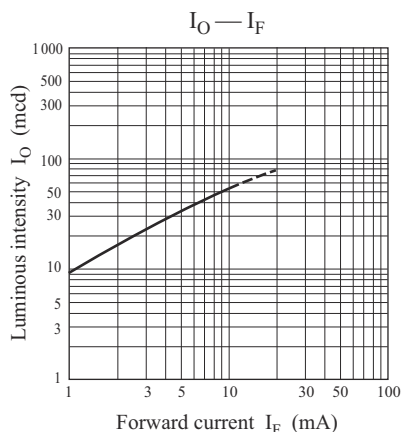
- Pure Green

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

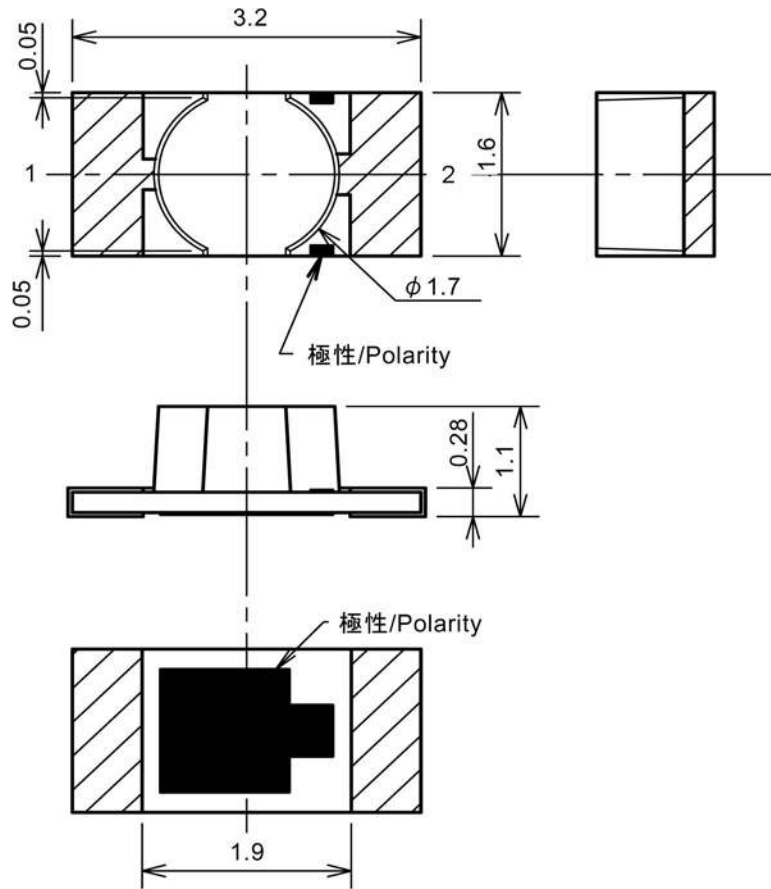
| Parameter                | Symbol          | Conditions           | Min  | Typ  | Max | Unit          |
|--------------------------|-----------------|----------------------|------|------|-----|---------------|
| Luminous intensity *     | $I_O$           | $I_F = 5 \text{ mA}$ | 14.4 | 34.0 |     | mcd           |
| Reverse current          | $I_R$           | $V_R = 5 \text{ V}$  |      |      | 10  | $\mu\text{A}$ |
| Forward voltage          | $V_F$           | $I_F = 5 \text{ mA}$ |      | 3.0  | 3.7 | V             |
| Peak emission wavelength | $\lambda_p$     | $I_F = 5 \text{ mA}$ |      | 525  |     | nm            |
| Spectral half band width | $\Delta\lambda$ | $I_F = 5 \text{ mA}$ |      | 45   |     | nm            |

Note) \*: Measurement tolerance:  $\pm 20\%$



■ Package (Unit: mm)

**KLTFN2K1100**



- Pin name
  - 1: Anode
  - 2: Cathode

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